

PATENT ABSTRACTS OF JAPAN

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(71)Applicant : SHINKO ELECTRIC IND CO LTD

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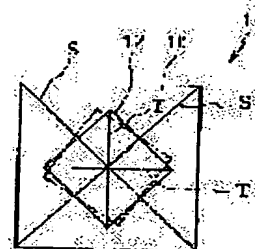
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(54) SEMICONDUCTOR DEVICE

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a semiconductor device capable of reducing warpage of a substrate.

SOLUTION: In a semiconductor device 14 in which the gap between a substrate 10 and a semiconductor chip 12 is filled up with an underfiller, while the semiconductor chip 12 is mounted on the substrate 10 made of an insulating material through-flip-chip connection of a connecting terminal formed on the substrate 10 with an electrode of the semiconductor chip 12, respective sides of the substrate 10 are made not to be in parallel with any side of the semiconductor chip 12, while the diagonal lines S of the substrate 10 are made not to be overlapped with the diagonal lines T of the semiconductor chip 12.



LEGAL STATUS

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